

EXS8310-B001
High Power SLED
830 nm UNCOOLED
TO-56 Package

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Confidentiality: **None**

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1. SCOPE

1.1 PURPOSE

The purpose of this document is to specify the electro-optical performance and dimensions of superluminescent light emitting diode (SLED) TO-56.

1.2 RESPONSIBILITY

EXALOS is responsible for establishing, implementing and maintaining this procedure. The Quality representative shall ensure that a timely Engineering Change Notice (ECN) is issued in accordance with EXALOS procedure for any changes.

2. REFERENCE DOCUMENT

- EXS-WI-0001 Visual Inspection Criteria SLED Chip on Submount Procedure
- MIL STD 883 C method.
- Bellcore GR-468-CORE

3. ELECTRO-OPTICAL PERFORMANCE ($T_{SLED} = 25^{\circ}C$)

Parameter	Symbol	Min	Typ	Max	Unit
Operating Current	I_F	0		100	mA
Power ex-facet	P_o	5	7		mW
Center Wavelength*	λ_c	800	820	840	nm
Bandwidth FWHM*		20	25		nm
Spectral ripple [RB=0.1 nm]			0.2	0.4	dB
Monitor Diode Current	I_{MPD}		1300 [†]		μA
Vertical Far Field Angle FWHM			40		degrees
Horizontal Far Field Angle FWHM			20		degrees

*Spectral verification is performed by sampling at the manufacturing batch level. Manufacturing batches are defined by epitaxial wafer growth run.

[†] Measurement conditions:

- $I_F = I_F$ Max
- Monitor PD bias voltage: 0 Volts

Input resistance of the Monitor PD current measurement circuit ~ 6 Ohm

4. ABSOLUTE MAXIMUM RATINGS

Stresses beyond the absolute maximum ratings may cause permanent damage to the device.
Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Parameter	Symbol	Cond.	Min	Max	Unit
Reverse voltage	V_R			-2	V
Forward voltage	V_F	$I_{F,max}$		2.5	V
Storage temperature	T_{stg}		-40	85	°C
Operating temperature	T_{op}	$I_{F,max}$	-20	65	°C
Lead soldering temperature				260	°C
ESD		human b.m		500	V
Monitor diode reverse bias voltage	V_{Bias}		0	-2	V

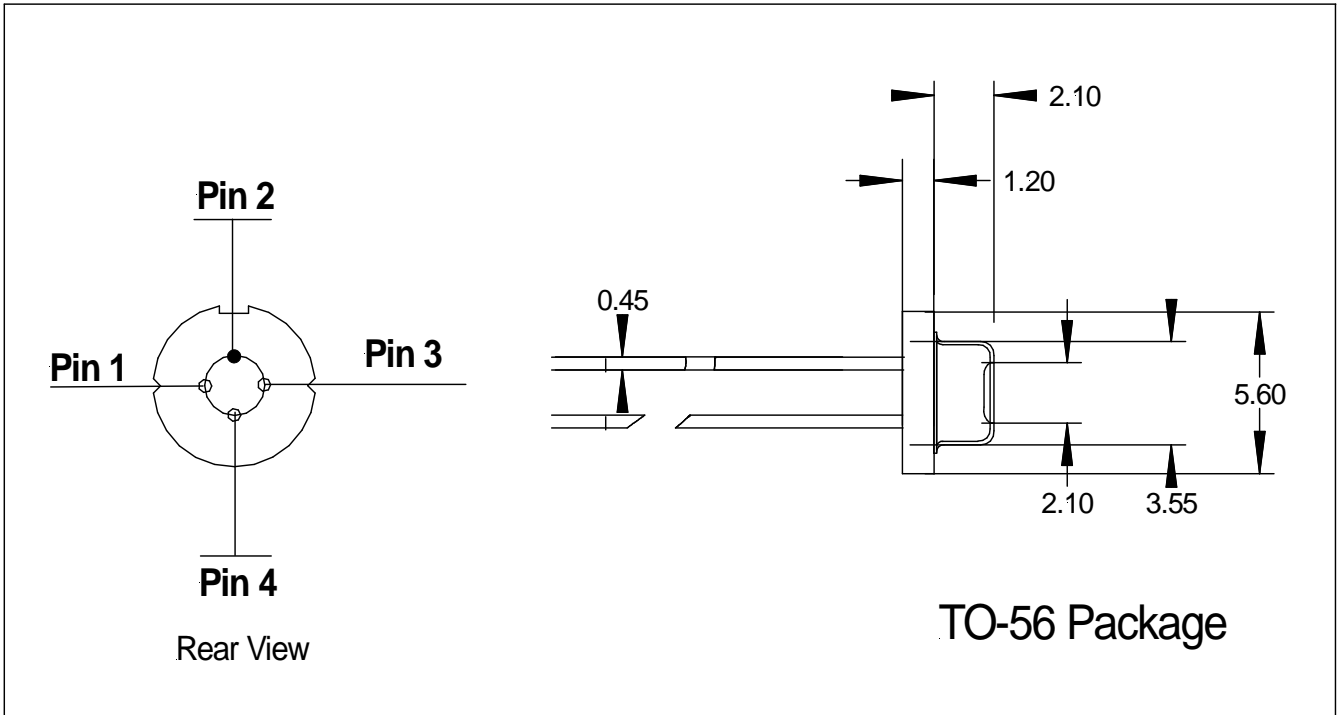
5. SCREENING (EXS8310-B001)

The produced 830nm SLED Module is required to meet all operating conditions specified in Table 4.1, Electro-Optical Performance Specifications after being subjected to the following screening tests.

Test Item	Test Conditions	Reference	Sample
Hermetic Seal	Fine leak :	MIL-STD-883, Method 1014	100 %
	Max. leak rate 5×10^{-8} atm.cc/sec	Condition A	
Temperature Cycling	Gross leak :	MIL-STD-883, Method 1014	100 %
		Condition C	
Temperature Cycling	-40°C to +85°C, ramp rate $\geq 5^\circ$ C/min 20 cycles	MIL-STD-883, Method 1010	100%
Burn-in	60 hours at 50°C – 120mA Delta P nominal < 20%		100%

6. PACKAGE DIMENSIONS [mm]

Tolerances: See section 6.1



TO-CAN	
Pin	Function
1	MONITOR DIODE ANODE
2	SLED (-), CASE, MONITOR DIODE CATHODE
3	SLED (+)
4	NC

Attention

Prior to connecting the SLED module to the driver using constant power mode, make sure that your SLED driver supports the so-called "Common laser cathode/photodiode cathode" arrangement and the connections are set accordingly. If this is not the case do not connect the SLED, otherwise it may result in permanent damage to the SLED.

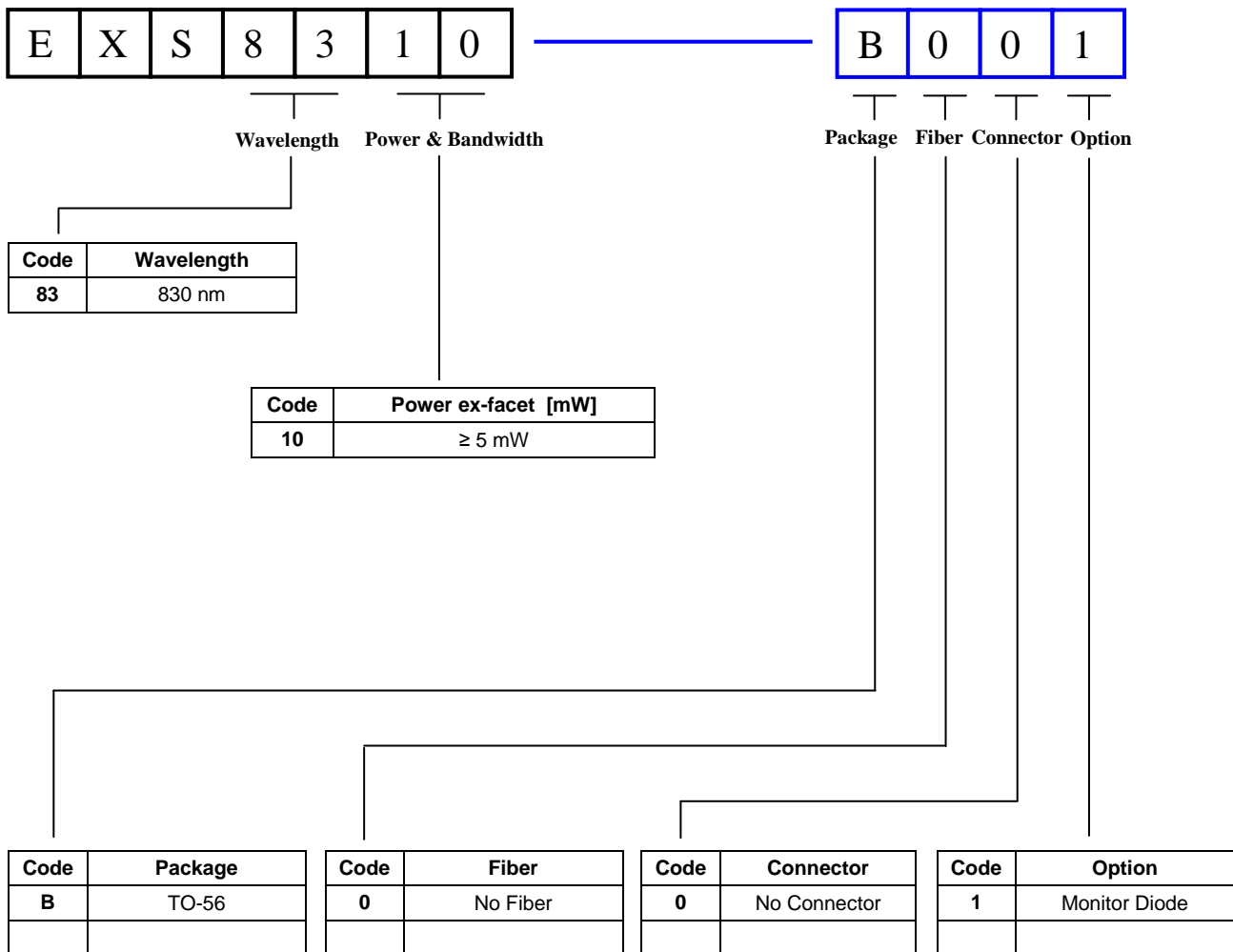
7. IMPORTANT NOTES

1. Avoid electrostatic discharges, which may destroy the SLED.
2. Never use the TO-CAN die without heat sinking.
3. Adequate eye protection against laser radiation should be used while handling and operating the module.
4. EXALOS declines any responsibility if the device is used in applications where human life may be endangered.
5. Back reflections may influence the output power and spectral characteristics of the SLED. The use of optical isolators and/or angled connectors is recommended. Back reflections of less than -30dB are recommended.

8. ORDERING INFORMATION

Please use the following code system to order products from EXALOS:

SLED EXS8310-B001 Product coding:



9. REVISION HISTORY

Revision History				
Rev.	Description	ECN Number	Date (ECN)	Released
1.0	Original version	-	-	23.08.04
2.0	Add additional drawings of mechanical dimensions of package, add monitor diode specification and conditions, add typical far field angle	EXS-EC-0159	29.08.05	29.08.05
2.1	Minor format changes	EXS-EC-0245	08.08.07	08.08.07
2.2	Spectral verification performed by epitaxial wafer growth run, Change burn-in at 120mA, 50°C instead of (70°C, 1 00mA)	EXS-EC-0315	03.02.09	03.02.09